

# GW5A series of FPGA Products

# **Data Sheet**

DS1103-1.0E, 6/29/2023

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# **Revision History**

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# 1 General Description

GOWINSEMI's GW5A series of FPGA products are the 5thgeneration of the Arora family with rich internal resources, including highperformance DSP resources with a new architecture and support for AI computing, high-speed LVDS interfaces, and rich BSRAM resources. At the same time, the GW5A series of FPGA provide independentlydeveloped DDR3 and a variety of packages. They are suitable for applications such as low power, high performance and compatibility designs.

GOWINSEMI provides a new generation of FPGA hardware development environment that supports FPGA synthesis, placement & routing, bitstream generation and download, etc.

#### 1.1 Features

- Lower power consumption
  - 22nm SRAM process
  - Core Power (LV version): 0.9V/ 1.0V
  - Core voltage (EV version): 1.2V<sup>[1]</sup>

#### Note

[1] The EV version (supported by GW5A-25) has a built-in LDO and supports 1.2V  $V_{\text{CC}}$ .

- Supports dynamic on/off of clock
- Abundant basic logic cells
  - GW5A-25 provides 23K LUT4s
  - GW5A-138 provides up to 138K LUT4s
  - Supports shadow SRAMs
- Block SRAMs with multiple modes
  - Supports Dual Port, Single Port, and Semi Dual Port
  - Supports bytes write enable
  - Supports ECC detection and error correction
- Supports MIPI D-PHY RX hard core

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- Supports MIPI DSI and MIPI CSI-2 RX
- Up to 2.5 Gbps per MIPI lane
- Supports up to eight data lanes and two clock lanes, with the max.
   transmission speed up to 20Gbps
- Supports MIPI D-PHY RX/TX hard core (GW5A-25)
  - Supports MIPI DSI and MIPI CSI-2 RX/TX
  - Up to 2.5 Gbps per MIPI lane(RX/TX)
  - Supports up to 4 data lanes and 1 clock lane
- GPIO supports MIPI D-PHY RX (GW5A-138)
  - GPIO can be configured as MIPI DSI and MIPI CSI-2 RX interfaces
  - Up to 1.5 Gbps per MIPI lane
- GPIO supports D-PHY RX/TX (GW5A-25)
  - GPIO can be configured as MIPI DSI and MIPI CSI-2 RX/TX interfaces
  - Up to 1.2 Gbps per MIPI lane
- High performance DSP blocks with a new architecture
  - High performance digital signal processing
  - Supports 27 x 18, 12 x 12, 27 x 36 multiplier and 48-bit accumulator
  - Supports cascading of multipliers
  - Supports pipeline mode and bypass mode
  - Pre-addtion operation for filter function
  - Supports barrel shifter
- A new and flexible X-channel oversampling ADC with high accuracy, no external voltage source required
  - 60dB SNR
  - 1kHz Signal Bandwidth
- Supports multiple SDRAM interfaces, up to DDR3 1333 Mbps (GW5A-138) or 1066 Mbps (GW5A-25)
- Multiple I/O standards
  - Hysteresis option for input signals
  - Supports drive strengths of 2mA<sup>[1]</sup>, 4mA, 6mA<sup>[1]</sup>, 8mA,16mA, 24mA<sup>[2]</sup>, etc.

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- [1] 2mA and 6mA are only supported by GW5A-25.
- [2] 24mA is only supported by GW5A-138.
- Individual Bus Keeper, Pull-up, Pull-down, and Open Drain options
- Hot Socket
- 16 global clocks, 6/12 high-performance PLLs, 16/24 high speed clocks
- Configuration & Programming
  - JTAG configuration
  - Four GowinConfig configuration modes: SSPI, MSPI, CPU, SERIAL
  - Supports programming the SPI Flash directly in JTAG and SSPI modes; For other modes, you can program the SPI Flash using IP
  - Supports background upgrade
  - Supports bitstream file encryption and security bit settings
  - Supports configuration memory soft error recovery (CMSER)
  - Supports mDRP
  - Supports OTP. Offers a unique 64-bit DNA identifier for each device

## 1.2 Product Resources

**Table 1-1 Product Resources** 

Device	GW5A-25	GW5A-138
LUT4	23040	138240
Flip-Flop (REG)	23040	138240
Distributed Static Random Access Memory SSRAM(Kb)	180	1080
Block Static Random Access Memory BSRAM(Kb)	1008	6120
Number of BSRAMs BSRAM	56	340
DSP (27-bit x 18-bit)	28	298
Maximum phase locked loop <sup>[1]</sup> (PLLs)	6	12
Global Clocks	16	16
High-speed Clocks	16	24
LVDS Gbps	1.25	1.25
DDR3 Mbps	1066	1333
MIPI DPHY hard core	2.5Gbps (Rx/Tx), 4 data lanes 1 clock lanes	2.5Gbps (Rx) 8 data lanes 2 clock lanes

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Device	GW5A-25	GW5A-138
ADC	1	2
Number of GPIO banks	8[2]	6
Maximum number of I/Os	236	376
Core voltage	0.9V/1.0V/1.2V <sup>[3]</sup>	0.9V/1.0V

- [1] Different packages support different numbers of PLLs.
- [2] In addition to GPIO Banks, there is one JTAG Bank with four I/Os and one Config Bank with one I/O.
- [3] The EV version has a built-in LDO and supports 1.2V Vcc.

Table 1-2 Package Information and Maximum Number of User I/Os

Package	Pitch (mm)	Size (mm)	GW5A-25	GW5A-138
MG121N	0.5	6 x 6	86(38)	_
UG324S	0.8	15 x 15	239(116)	_
UG256C	0.8	14 x 14	191(90)	_
PG256C	1.0	17 x 17	191(90)	_
PG256S	1.0	17 x 17	194 (93)	_
UG324	8.0	15 x 15	222(104)	_
UG324A	8.0	15 x 15	_	222(106)
MG196S	0.5	8 x 8	114(53)	_
UG225S	0.8	13 x 13	168(80)	_
LQ100	0.5	14 x 14	80 (36)	_

#### Note!

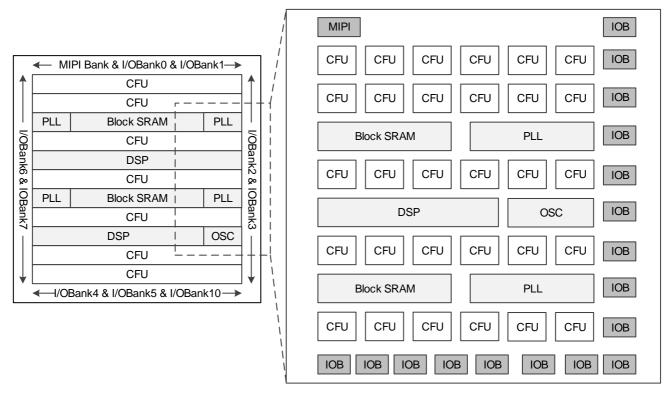
[1] The package types in this data sheet are written with abbreviations. See <u>4.1 Part Name</u> for further information.

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# 2 Architecture

## 2.1 Architecture

Figure 2-1 Architecture Diagram (GW5A-138)



See Figure 2-1 for an overview of the architecture of the GW5A-138 device. Please refer to Table 1-1 for more information on its internal resources. The core of the device is an array of Configurable Logic Units (CFU) surrounded by IO blocks. Besides, BSRAMs, DSP blocks, MIPI D-PHY, ADC, PLLs, and on chip oscillators are provided.

Configurable Function Unit (CFU) is the base cell for the array of the GW5A series of FPGA Products. Devices with different capacities have different numbers of rows and columns. CFU can be configured as LUT4 mode, ALU mode, and memory mode. For more detailed information, see <u>2.2 Configurable Function Units</u>.

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The I/O resources in the GW5A series of FPGA products are arranged around the periphery of the devices in groups referred to as banks. I/O resources support multiple I/O standards, and support regular mode, SRD mode, generic DDR mode, and DDR\_MEM mode. For more detailed information, see <a href="mailto:2.3">2.3</a> Input/Output Blocks.

The BSRAM is embedded as a row in GW5A series of FPGA products. Each BSRAM has a maximum capacity of 36Kbits and consists of two 18Kbits BSRAMs. It supports multiple configuration modes and operation modes. For more detailed information, see <u>2.4 Block SRAM</u> (BSRAM).

GW5A series of FPGA products are embedded with a brand-new DSP, which can meet the high-performance digital signal processing requirements. For details, refer to <u>2.5 DSP Blocks</u>.

GW5A series of FPGA products provide a MIPI D-PHY hardcore supporting the "MIPI Alliance Standard for D-PHY Specification(V1.2)". For details, see 2.6 MIPI D-PHY.

GW5A series of FPGA products integrate a new and flexible oversampling ADC. For details, see 2.7 ADC.

GW5A series of FPGA products have embedded PLL resources. PLL blocks provide the ability to synthesize clock frequencies. Frequency adjustment (multiply and division), phase adjustment, and duty cycle can be adjusted using the configuration of parameters. This series of FPGAs also have an embedded programmable on-chip clock oscillator that supports clock frequencies ranging from 2.5 MHz to 105MHz, providing clocking resources for the MSPI mode. The on-chip clock oscillator also provides programmable user clocks. For more information, see <u>2.11 On</u> Chip Oscillator.

FPGA provides abundant CRUs, connecting all the resources in FPGA. For example, routing resources distributed in CFU and IOB connect resources in CFU and IOB. Routing resources can automatically be generated by Gowin software. In addition, the GW5A series of FPGA Products also provide abundant GCLKs, long wires (LW), global set/reset (GSR), and programming options, etc. For more details, see <u>2.9 Global Set/Reset (GSR)</u>, and <u>2.10 Programming & Configuration</u>.

# 2.2 Configurable Function Units

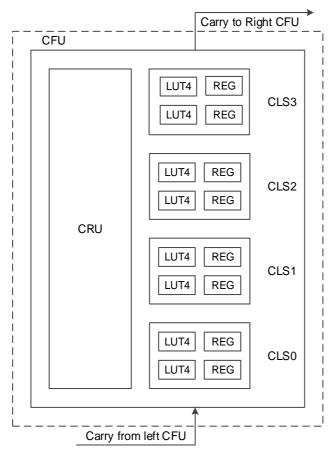
Configurable Function Units (CFUs) are the basic cells for the array of GOWINSEMI FPGA Products. Each basic cell consists of four Configurable Logic Sections (CLSs) and their routing resource Configurable Routing Units (CRUs). Each CLS includes two 4 input look-up-tables (LUTs) and two registers (REGs), as shown in Figure 2-2.

CLSs in the CFUs can be configured as basic look-up tables, arithmetic logic units, static random access memories, and read only memories according to application scenarios.

For more details, please see <u>UG303, Arora V Configurable Function</u> Unit (CFU) User Guide.

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Figure 2-2 CFU Structure View



# 2.3 Input/Output Blocks

The IOB in the GW5A series of FPGA products includes IO buffer, IO logic, and its routing unit. As shown in Figure 2-3, each IOB connects to two Pins (Marked as A and B). They can be used as a differential pair or as a single-ended input/output.

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**Differential Pair Differential Pair** "True" "Comp" "True" "Comp" PAD B PAD B PAD A PAD A Buffer Pair A & B Buffer Pair A & B 5 IO Logic IO Logic IO Logic IO Logic Α В В Routing Routing

Figure 2-3 IOB Structure View

#### **IOB Features:**

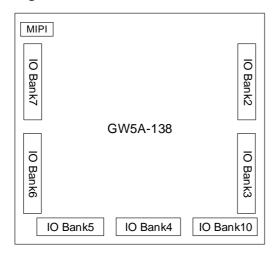
- V<sub>CCIO</sub> supplied with each bank
- All banks support True differential input
- Supports multiple levels: LVCMOS, PCI, LVTTL, SSTL, HSTL, LVDS, Mini LVDS, RSDS, PPDS, BLVDS
- Input hysteresis option
- Output drive strength option
- Individual bus keeper, weak pull-up, weak pull-down, and open drain option
- Hot socket
- IO logic supports SDR mode, DDR mode, etc.

# **2.3.1 I/O Buffer**

GW5A-138 has six GPIO Banks (Bank2~7) and a Bank for configuration (Bank 10), as shown in Figure 2-4. Bank 10 can also be used as an I/O Bank.

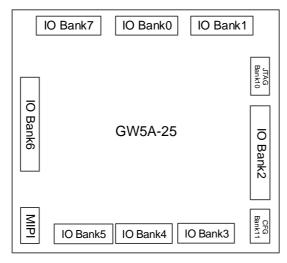
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Figure 2-4 Bank Distribution View of GW5A-138



GW5A-25 has eight GPIO Banks. Bank10 is a JTAG Bank with four IOs, Bank11 is a Config Bank with one IO, as shown in Figure 2-5.

Figure 2-5 Bank Distribution View of GW5A-25



Each Bank has its independent I/O power supply Vccio.

GW5A-25's  $V_{CCIO}$  can be set as 3.3V, 2.5V, 1.8V, 1.5V, 1.35V, or 1.2V. GW5A-138's  $V_{CCIO}$  can be set as 3.3V, 2.5V, 1.8V, 1.5V, 1.35V, 1.2V,

## or 1V. Note!

- GW5A-138: To support SSTL, HSTL, etc., each bank also provides one independent voltage source (VREF) as the reference voltage. You can choose from the internal reference voltage of the bank (0.6V, 0.675V, 0.75V, 0.9V, and (33%,42%,50%,58%)VCCIO) or the external reference voltage using any IO from the bank.
- GW5A-25: To support SSTL, HSTL, etc., each bank also provides one independent voltage source (VREF) as the reference voltage. You can choose from the internal reference voltage of the bank (0.6V, 0.75V, 0.9V, 1.25V, 1.5V, and (36%,50%,64%)VCCIO) or the external reference voltage using any IO from the bank.

The auxiliary voltage V<sub>CCX</sub> of GW5A-25 devices supports 2.5V~3.3V.

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The auxiliary voltage V<sub>CCX</sub> of GW5A-138 devices supports 1.8V.

Different banks in the GW5A series of FPGA Products support different on-chip resistor settings, including single-ended resistor and differential resistor. Single-ended resistor is set for SSTL/HSTL I/O. Differential resistor is set for LVDS/PPDS/ RSDS input. For more details, refer to UG304, Arora V Programmable IO (GPIO) User Guide.

#### Note!

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Before and during configuration, all GPIOs of the device have weak pull-up by default. The default I/O state is None after configuration is complete and it can be configured via the Gowin software. The status of configuration-related I/Os differs depending on the configuration mode.

For the  $V_{\text{CCIO}}$  requirements of different I/O standards, see Table 2-1, Table 2-2, Table 2-3, and Table 2-4.

Table 2-1 Output I/O Standards and Configuration Options supported by GW5A-

I/O output standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Drive Strength (mA)	Typical Applications
LVDS25		2.5/3.3	3.5/2.5/4.5/6	High-speed point- to-point data transmission
BLVDS25		2.5/3.3	3.5/2.5/4.5/6	Multi-point high- speed data transmission
RSDS	Differential(TLV DS)	2.5/3.3	3.5/2.5/4.5/6	High-speed point- to-point data transmission
MINILVDS		2.5/3.3	3.5/2.5/4.5/6	LCD timing driver interface and column driver interface
PPLVDS		2.5/3.3	3.5/2.5/4.5/6	LCD row/column driver
LVDS25E		2.5	8/4/12/16/24	High-speed point- to-point data transmission
BLVDS25E		2.5	8/4/12/16/24	Multi-point high- speed data transmission
MLVDS25E	Differential	2.5	8/4/12/16/24	LCD timing driver interface and column driver interface
RSDS25E		2.5	8/4/12/16/24	High-speed point- to-point data transmission
LVPECL33E		3.3	8/4/12/16/24	Universal interface
HSUL12D		1.2	8/4/12	LPDDR2
HSUL12D_I		1.2	8/4/12	LPDDR2
HSTL15D_I		1.5	8/4/12/16	Memory interface
HSTL15D_II <sup>[4]</sup>		1.5	8/4/12/16	Memory interface

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I/O output standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Drive Strength (mA)	Typical Applications
HSTL18D_I		1.8	8/4/12/16	Memory interface
HSTL18D_II		1.8	8/4/12/16	Memory interface
SSTL135D		1.35	8/4/12	Memory interface
SSTL15D		1.5	8/4/12/16	Memory interface
SSTL18D_I		1.8	8/4/12/16/24	Memory interface
SSTL18D_II		1.8	8/4/12/16/24	Memory interface
LPDDRD		1.8	8/4/12/16/24	LPDDR and Mobile DDR
LVCMOS10D		1.0	4	Universal interface
LVCMOS12D		1.2	4/8	Universal interface
LVCMOS15D		1.5	4/8/12	Universal interface
LVCMOS18D		1.8	4/8/12/16/24	Universal interface
LVCMOS25D		2.5	4/8/12/16/24	Universal interface
LVCMOS33D		3.3	8/4/12/16/24	Universal interface
HSUL12		1.2	8/4/12	Memory interface
HSTL12_I		1.2	8/4/12	Memory interface
HSTL15_I		1.5	8/4/12/16	Memory interface
HSTL15_ II		1.5	8/4/12/16	Memory interface
HSTL18_I		1.8	8/4/12/16/24	Memory interface
HSTL18_II		1.8	8/4/12/16/24	Memory interface
SSTL135		1.35	8/4/12	Memory interface
SSTL15		1.5	8/4/12/16	Memory interface
SSTL18_I		1.8	8/4/12/16/24	Memory interface
SSTL18_II	Single-ended	1.8	8/4/12/16/24	Memory interface
LVCMOS10		1.0		Universal interface
LVCMOS12		1.2	4/8	Universal interface
LVCMOS15		1.5	4/8/12	Universal interface
LVCMOS18		1.8	4/8/12/16/24	Universal interface
LVCMOS25		2.5	4/8/12/16/24	Universal interface
LVCMOS33/L VTTL33		3.3	8/4/12/16/24	Universal interface
LPDDR		1.8	8/4/12/16/24	LPDDR and Mobile DDR
PCI33		3.3	8/4/12/16/24	PC and embedded system

Table 2-2 Input I/O Standards and Configuration Options supported by GW5A-138

I/O Input Standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Hysteresis	Need V <sub>REF</sub>
MIPI	Differential	1.2	No	No
ADC_in		2.5/1.0/1.2/1.5/1.8/3.3	No	No

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I/O Input Standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Hysteresis	Need V <sub>REF</sub>
LVDS25		2.5/1.0/1.2/1.5/1.8/3.3	No	No
BLVDS25		2.5/1.0/1.2/1.5/1.8/3.3	No	No
RSDS		2.5/1.0/1.2/1.5/1.8/3.3	No	No
MINILVDS		2.5/1.0/1.2/1.5/1.8/3.3	No	No
PPLVDS		2.5/1.0/1.2/1.5/1.8/3.3	No	No
HSUL12D		1.2/1.0/1.5/1.8/2.5/3.3	No	No
HSTL12D_I		1.2/1.0/1.5/1.8/2.5/3.3	No	No
HSTL15D_I		1.5/1.0/1.2/1.8/2.5/3.3	No	No
HSTL15D_II		1.5/1.0/1.2/1.8/2.5/3.3	No	No
HSTL18D_I		1.8/1.0/1.2/1.5/2.5/3.3	No	No
HSTL18D_II		1.8/1.0/1.2/1.5/2.5/3.3	No	No
SSTL135D		1.35/ 1.0/ 1.2/ 1.5/ 1.8/ 2.5/ 3.3	No	No
SSTL15D		1.5/1.0/1.2/1.8/2.5/3.3	No	No
SSTL18D_I		1.8/1.0/1.2/1.5/2.5/3.3	No	No
SSTL18D_II		1.8/1.0/1.2/1.5/2.5/3.3	No	No
LPDDRD		1.8/1.0/1.2/1.5/2.5/3.3	No	No
LVCMOS10D		1.0/1.2/1.5/1.8/2.5/3.3	No	No
LVCMOS12D		1.2/1.0/1.5/1.8/2.5/3.3	No	No
LVCMOS15D		1.5/1.0/1.2/1.8/2.5/3.3	No	No
LVCMOS18D		1.8/1.0/1.2/1.5/2.5/3.3	No	No
HSUL12		1.2	Yes	No
HSTL12_I		1.2	Yes	No
HSTL15_I		1.5	Yes	No
HSTL15_II		1.5	Yes	No
HSTL18_I		1.8	Yes	No
HSTL18_II		1.8	Yes	No
SSTL135		1.35	Yes	No
SSTL15		1.5	Yes	No
SSTL18_I	Cinale anded	1.8	Yes	No
SSTL18_II	Single-ended	1.8	Yes	No
LVCMOS10		1.0	Yes	No
LVCMOS10UD12		1.2	Yes	No
LVCMOS10UD15		1.5	Yes	No
LVCMOS10UD18		1.8	Yes	No
LVCMOS10UD25		2.5	Yes	No
LVCMOS10UD33		3.3	Yes	No
LVCMOS12		1.2	Yes	No
LVCMOS15		1.5	Yes	No

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I/O Input Standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Hysteresis	Need V <sub>REF</sub>
LVCMOS15OD10		1.0	Yes	No
LVCMOS150D12		1.2	Yes	No
LVCMOS15UD18		1.8	Yes	No
LVCMOS15UD25		2.5	Yes	No
LVCMOS15UD33		3.3	Yes	No
LVCMOS18		1.8	Yes	No
LVCMOS18OD10		1.0	Yes	No
LVCMOS18OD12		1.2	Yes	No
LVCMOS18OD15		1.5	Yes	No
LVCMOS18UD25		2.5	Yes	No
LVCMOS18UD33		3.3	Yes	No
LVCMOS25		2.5	Yes	No
LVCMOS25UD33		3.3	Yes	No
LVCMOS33/LVTT L33		3.3	Yes	No
LVCMOS33OD25		2.5	Yes	No
LPDDR		1.8	Yes	No
PCI33		3.3	Yes	No
VREF1_DRIVER		1.8/1.2/1.35/1.5	No	Yes

Table 2-3 Output I/O Standards and Configuration Options supported by GW5A-

I/O output standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Drive Strength (mA)	Typical Applications
MIPI	Differential (MIPI)	1.2	-	Mobile Industry Processor Interface
LVDS25		2.5/3.3	3.5/2.5/4.5/6	High-speed point- to-point data transmission
BLVDS25		2.5/3.3	3.5/2.5/4.5/6	Multi-point high- speed data transmission
RSDS	Differential(TLV DS)	2.5/3.3	3.5/2.5/4.5/6	High-speed point- to-point data transmission
MINILVDS		2.5/3.3	3.5/2.5/4.5/6	LCD timing driver interface and column driver interface
PPLVDS		2.5/3.3 3.5/2.5/4.5/6		LCD row/column driver
LVDS25E	2.5 8/2/4/6/12/16		8/2/4/6/12/16	High-speed point- to-point data transmission
BLVDS25E	- Differential	2.5	8/2/4/6/12/16	Multi-point high- speed data transmission

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I/O output standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Drive Strength (mA)	Typical Applications
MLVDS25E		2.5	8/2/4/6/12/16	LCD timing driver interface and column driver interface
RSDS25E		2.5	8/2/4/6/12/16	High-speed point- to-point data transmission
LVPECL33E		3.3	8/2/4/6/12/16	Universal interface
HSUL12D		1.2	8/2/4/6	LPDDR2
HSUL12D_I		1.2	8/2/4/6	LPDDR2
HSTL15D_I		1.5	8/4/12	Memory interface
HSTL18D_I		1.8	8/2/4/6/12/16	Memory interface
HSTL18D_II		1.8	8/2/4/6/12/16	Memory interface
SSTL12D_I		1.2	8/2/4/6	Memory interface
SSTL135D_I		1.35	8/2/4/6	Memory interface
SSTL15D_I		1.5	8/2/4/6/12	Memory interface
SSTL18D_I		1.8	8/2/4/6/12/16	Memory interface
SSTL18D_II		1.8	8/2/4/6/12/16	Memory interface
SSTL25D_I		2.5	8/2/4/6/12/16	Memory interface
SSTL25D_ II.		2.5	8/2/4/6/12/16	Memory interface
SSTL33D_I		3.3	8/2/4/6/12/16	Memory interface
SSTL33D_II		3.3	8/2/4/6/12/16	Memory interface
LPDDRD		1.8	8/2/4/6/12/16	LPDDR and Mobile DDR
LVCMOS10D		1.0	2/4	Universal interface
LVCMOS12D		1.2	8/2/4/6	Universal interface
LVCMOS15D		1.5	8/2/4/6/12	Universal interface
LVCMOS18D		1.8	8/2/4/6/12/16	Universal interface
LVCMOS25D		2.5	8/2/4/6/12/16	Universal interface
LVCMOS33D		3.3	8/2/4/6/12/16	Universal interface
HSUL12		1.2	8/2/4/6	Memory interface
HSTL12_I		1.2	8/2/4/6	Memory interface
HSTL15_I		1.5	8/2/4/6/12	Memory interface
HSTL18_I		1.8	8/2/4/6/12/16	Memory interface
HSTL18_II		1.8	8/2/4/6/12/16	Memory interface
SSTL12_I	Single-ended	1.2	8/2/4/6	Memory interface
SSTL135_I		1.35	8/2/4/6	Memory interface
SSTL15_I		1.5	8/2/4/6/12	Memory interface
SSTL18_I		1.8	8/2/4/6/12/16	Memory interface
SSTL18_II		1.8	8/2/4/6/12/16	Memory interface
SSTL25_I		2.5	8/2/4/6/12/16	Memory interface

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I/O output standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Drive Strength (mA)	Typical Applications
SSTL25_II		2.5	8/2/4/6/12/16	Memory interface
SSTL33_I		3.3	8/2/4/6/12/16	Memory interface
SSTL33_II		3.3	8/2/4/6/12/16	Memory interface
LVCMOS10		1.0	2/4	Universal interface
LVCMOS12		1.2	8/2/4/6	Universal interface
LVCMOS15		1.5	8/2/4/6/12	Universal interface
LVCMOS18		1.8	8/2/4/6/12/16	Universal interface
LVCMOS25		2.5	8/2/4/6/12/16	Universal interface
LVCMOS33/L VTTL33		3.3	8/2/4/6/12/16	Universal interface
LPDDR		1.8	8/2/4/6/12/16	LPDDR and Mobile DDR
PCI33		3.3	8/2/4/6/12/16	PC and embedded system

Table 2-4 Input I/O Standards and Configuration Options Supported by GW5A-25

I/O Input Standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Hysteresis	Need V <sub>REF</sub>
MIPI		1.2	No	No
ADC_in		2.5/1.0/1.2/1.5/1.8/3.3	No	No
LVDS25		2.5/1.0/1.2/1.5/1.8/3.3	No	No
BLVDS25		2.5/1.0/1.2/1.5/1.8/3.3	No	No
RSDS		2.5/1.0/1.2/1.5/1.8/3.3	No	No
MINILVDS		2.5/1.0/1.2/1.5/1.8/3.3	No	No
PPLVDS		2.5/1.0/1.2/1.5/1.8/3.3	No	No
HSUL12D		1.2/1.0/1.5/1.8/2.5/3.3	No	No
HSTL12D_I		1.2/1.0/1.5/1.8/2.5/3.3	No	No
HSTL15D_I		1.5/1.0/1.2/1.8/2.5/3.3	No	No
HSTL18D_I		1.8/1.0/1.2/1.5/2.5/3.3	No	No
HSTL18D_II	Differential	1.8/1.0/1.2/1.5/2.5/3.3	No	No
SSTL135D_I		1.35/ 1.0/ 1.2/ 1.5/ 1.8/ 2.5/ 3.3	No	No
SSTL15D_I		1.5/1.0/1.2/1.8/2.5/3.3	No	No
SSTL18D_I		1.8/1.0/1.2/1.5/2.5/3.3	No	No
SSTL18D_II		1.8/1.0/1.2/1.5/2.5/3.3	No	No
SSTL2D_I		2.5/1.0/1.2/1.5/1.8/3.3	No	No
SSTL2D_II.		2.5/1.0/1.2/1.5/1.8/3.3	No	No
SSTL3D_I		3.3/1.0/1.2/1.5/1.8/2.5	No	No
SSTL3D_II.		3.3/1.0/1.2/1.5/1.8/2.5	No	No
LPDDRD		1.8/1.0/1.2/1.5/2.5/3.3	No	No
LVCMOS10D		1.0/1.2/1.5/1.8/2.5/3.3	No	No
LVCMOS12D		1.2/1.0/1.5/1.8/2.5/3.3	No	No

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I/O Input Standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Hysteresis	Need V <sub>REF</sub>
LVCMOS15D		1.5/1.0/1.2/1.8/2.5/3.3	No	No
LVCMOS18D		1.8/1.0/1.2/1.5/2.5/3.3	No	No
LVCMOS25D		2.5/1.0/1.2/1.5/1.8/3.3	No	No
LVCMOS33D		3.3/1.0/1.2/1.5/2.5/1.8	No	No
HSUL12		1.2	Yes	No
HSTL12_I		1.2	Yes	No
HSTL15_I		1.5	Yes	No
HSTL15_II		1.5	Yes	No
HSTL18_I		1.8	Yes	No
HSTL18_II		1.8	Yes	No
SSTL135_I		1.35	Yes	No
SSTL15_I		1.5	Yes	No
SSTL18_I		1.8	Yes	No
SSTL18_II		1.8	Yes	No
SSTL2_I		2.5	Yes	No
SSTL2_II		2.5	Yes	No
SSTL3_I		3.3	Yes	No
SSTL3_II		3.3	Yes	No
LVCMOS10		1.0	Yes	No
LVCMOS12		1.2	Yes	No
LVCMOS15		1.5	Yes	No
LVCMOS18	Single-ended	1.8	Yes	No
LVCMOS25		2.5	Yes	No
LVCMOS33/LVTT L33		3.3	Yes	No
LPDDR		1.8	Yes	No
PCI33		3.3	Yes	No
LVCMOS10UD12		1.2	Yes	No
LVCMOS10UD15		1.5	Yes	No
LVCMOS10UD18		1.8	Yes	No
LVCMOS10UD25		2.5	Yes	No
LVCMOS10UD33		3.3	Yes	No
LVCMOS12OD10		1.0	Yes	No
LVCMOS12UD15		1.5	Yes	No
LVCMOS12UD18		1.8	Yes	No
LVCMOS12UD25		2.5	Yes	No
LVCMOS12UD33		3.3	Yes	No
LVCMOS15OD10		1.0	Yes	No
LVCMOS150D12		1.2	Yes	No

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I/O Input Standard	Single-ended / Differential	Bank V <sub>CCIO</sub> (V)	Hysteresis	Need V <sub>REF</sub>
LVCMOS15UD18		1.8	Yes	No
LVCMOS15UD25		2.5	Yes	No
LVCMOS15UD33		3.3	Yes	No
LVCMOS18OD10		1.0	Yes	No
LVCMOS18OD12		1.2	Yes	No
LVCMOS18OD15		1.5	Yes	No
LVCMOS18UD25		2.5	Yes	No
LVCMOS18UD33		3.3	Yes	No
LVCMOS25OD10		2.5	Yes	No
LVCMOS25OD12		3.3	Yes	No
LVCMOS25OD15		1.5	Yes	No
LVCMOS25OD18		1.8	Yes	No
LVCMOS25UD33		3.3	Yes	No
LVCMOS33OD10		1.0	Yes	No
LVCMOS33OD12		1.2	Yes	No
LVCMOS33OD15		3.3	Yes	No
LVCMOS33OD18		1.8	Yes	No
LVCMOS33OD25		2.5	Yes	No
VREF1_DRIVER		1.8/1.2/1.35/1.5	No	Yes

# 2.3.2 I/O Logic

Figure 2-6 shows the I/O logic output of GW5A series of FPGA products.

Figure 2-6 I/O Logic Output

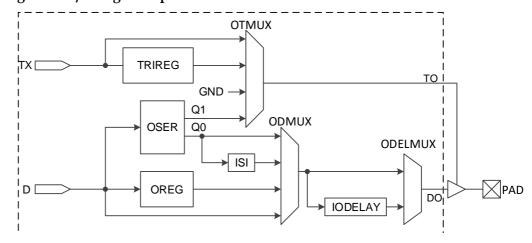
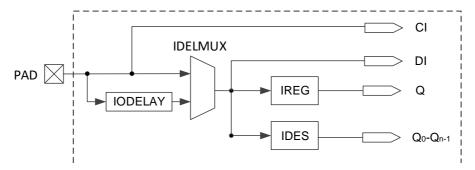


Figure 2-7 shows the I/O logic input of the GW5A series of FPGA products.

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Figure 2-7 I/O Logic Input



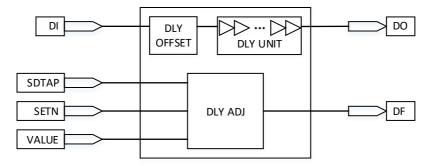
CI is a GCLK input signal and cannot be connected to the fabric; DI is input directly to the fabric.

Descriptions of the I/O logic modules of GW5A series of FPGA products are presented below.

#### **Delay Modules**

See Figure 2-8 for an overview of the IODELAY. Each I/O of GW5A includes IODELAY, providing a total of 256 (0~255) delays, with a single-step delay time of about 15.5ps. The total delay time achieved by IODELAY is DLYOFFSET+DLY UNIT\*SDTAP.

Figure 2-8 IODELAY



There are three ways to control the delay:

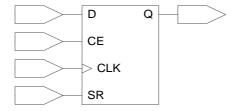
- Static control.
- Dynamic control, which can be combined with logic function circuits to achieve dynamic delay adjustment.
- Adaptive control.

#### I/O Register

See Figure 2-9 for the I/O register in GW5A series of FPGA products. Each I/O of the GW5A series of FPGA products provides one input register (IREG), one output register (OREG), and one tristate Register (TREG).

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Figure 2-9 Diagram of I/O registers of GW5A



- CE can be either active ow (0: enable) or active high (1: enable).
- CLK can be either rising edge trigger or falling edge trigger.
- SR can be either synchronous/asynchronous SET or RESET or disable.
- The registers can be programmed as registers(DFFs) or latches.

#### De-serializer DES and Serializer SER

The GW5A series of FPGA Products support serialization and deserialization of various ratios, as shown in the following table:

Table2-5 DES /SER Ratios Supported by the GW5A Series of FPGA Products

	Ratios Supported
Input logic	1:2 / 1:4 / 1:7 / 1:8 / 1:10 / 1:14 / 1:16 / 1:32
Output logic	2:1 / 4:1/ 7:1 / 8:1 / 10:1 / 16:1 / 14:1 <sup>[1]</sup>

#### Note!

Only GW5A-25 supports 14:1 OSER.

# 2.3.3 I/O Logic Modes

The I/O Logic in GW5A series of FPGA products supports several modes. In each operation, the I/O (or I/O differential pair) can be configured as output, input, and INOUT or tristate output (output signal with tristate control).

For more details, refer to <u>UG304, Arora V Programmable IO (GPIO)</u> <u>User Guide</u>.

# 2.4 Block SRAM (BSRAM)

#### 2.4.1 Introduction

GW5A series of FPGA products provide abundant block SRAM resources. These memory resources are distributed throughout the FPGA array in the form of rows. Therefore, they are called block static random access memories (BSRAMs). Up to 36Kbits can be configured for each BSRAM. There are five operation modes: Single Port mode, Dual Port mode, Semi Dual Port mode with ECC function, and ROM mode.

An abundance of BSRAM resources provide a guarantee for the user's high-performance design. BSRAM's features:

- Up to 18Kbits per BSRAM
- Clock frequency up to 380MHz (230MHz in Read-before-write mode)

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- Supports Single Port mode
- Supports Dual Port mode
- Supports Semi Dual Port Mode
- Supports ECC detection and error correction Function
- Supports ROM Mode
- Data width up to 72bits
- Dual Port and Semi-dual Port support independent clocks and independent data width
- Read mode supports Register Output and Bypass Output
- Write mode supports Normal mode, read-before-write mode<sup>[1]</sup>, and write-through mode

[1] Only GW5A-25 supports read-before-write mode.

# 2.4.2 Configuration Mode

BSRAMs in the GW5A series of FPGA products support various data widths. See Table 2-6.

**Table 2-6 Memory Size Configuration** 

Capacity	Single Port Mode			Semi Dual Port Mode with ECC Function	Read Only Mode
	16K x 1	16K x 1	16K x 1	_	16K x 1
	8K x 2	8K x 2	8K x 2	_	8K x 2
16Khita	4K x 4	4K x 4	4K x 4	_	4K x 4
16Kbits	2K x 8	2K x 8	2K x 8	_	2K x 8
	1K x 16	1K x 16	1K x 16	_	1K x 16
	512 x 32	_	512 x 32	_	512 x 32
	2K x 9	2K x 9	2K x 9	_	2K x 9
18Kbits	1K x 18	1K x 18	1K x 18	_	1K x 18
	512 x 36	_	512 x 36	_	512 x 36
36Kbits	_	_	_	512 x 72	_

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#### **Single Port Mode**

In the single port mode, BSRAM can write to or read from one port at one clock edge. It supports 2 read modes (bypass mode and pipeline mode) and 3 write modes (normal mode, write-through mode, and read-before-write mode<sup>[1]</sup>). In Normal-Write Mode, the written data will be stored in the internal memory array. In Write—through Mode, the written data will not only be stored in the internal memory array, but also be written to the output of BSRAM. When the output register is bypassed, the new data will show at the same write clock rising edge.

#### Note!

[1] Only GW5A-25 supports read-before-write mode.

For more information on single port mode, please refer to <u>UG300</u>, <u>Arora V BSRAM & SSRAM User Guide</u>.

#### **Dual Port Mode**

BSRAM supports Dual Port mode. It supports 2 read modes (bypass mode and pipeline mode) and 3 write modes (normal mode, write-through mode, and read-before-write mode<sup>[1]</sup>). The applicable operations are as follows:

- Two independent read, reading data from any given address.
- Two independent write, writing data to any address that is different.
- An independent read and an independent write at different clock frequencies.

#### Note!

- [1] Only GW5A-25 supports read-before-write mode.
- In Dual-port mode, Port A and Port B can read from or write to the same address. Null or repeated reads do not damage the storage module.
- In Dual-port mode, when Port A and Port B write to the same address at the same time, the dual ports writing fail at the same time.
- When Port A reads, Port B writes, and they access the same address, the write port succeeds, but the read port fails, and the output data is unknown. BSRAM contents are the values from the write port.

Dual Port supports independent read/write clocks and independent read/write data width. For more information on dual port mode, please refer to <u>UG300</u>, <u>Arora V BSRAM & SSRAM User Guide</u>.

#### Semi Dual Port Mode

Semi-dual ports support independent read/write operations in the form of A port write-only ("Normal mode") and B port read-only. When Port A reads, Port B writes, and they access the same address, the write port succeeds, but the read port fails, and the output data is unknown. BSRAM contents are the values from the write port.

Semi-dual Port supports independent read/write clocks and independent read/write data width. For more information on semi dual port mode, please refer to <u>UG300</u>, <u>Arora V BSRAM & SSRAM User Guide</u>.

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#### Semi Dual Port Mode with ECC Function

Semi-dual ports with ECC Function support independent read/write operations in the form of A port write-only and B port read-only. Independent read/write data width is also supported. This mode provides ECC function. For more information on this mode, please refer to UG300, Arora V BSRAM & SSRAM User Guide.

#### **Read Only Mode**

BSRAM can be configured as ROM. The ROM can be initialized during the device configuration stage, and the ROM data needs to be provided in the initialization file. Initialization completes during the device power-on process.

Each BSRAM can be configured as one 16 Kbits ROM. For more information on read only mode, please refer to <u>UG300, Arora V BSRAM & SSRAM User Guide</u>.

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## 2.4.3 Data Width Configuration

BSRAMs in the GW5A series of FPGA products support independent data width for read/write operations. In Dual Port mode, Semi Dual Port mode, and Semi Dual Port mode with ECC function (GW5A-138), the data width for read/write operations can be different. For the data width supported by Port A and Port B, see Table 2-7, Table 2-8, and Table 2-9.

Table 2-7 Read/Write Data Width	Configuration in Dual Port Mode

Consoity	Dort P	Port A							
Capacity	Port B	16K x 1	8K x 2	4K x 4	2K x 8	1K x 16	2K x 9	1K x 18	
	16K x 1	Yes	Yes	Yes	Yes	Yes	N/A	N/A	
	8K x 2	Yes	Yes	Yes	Yes	Yes	N/A	N/A	
16Kbits	4K x 4	Yes	Yes	Yes	Yes	Yes	N/A	N/A	
	2K x 8	Yes	Yes	Yes	Yes	Yes	N/A	N/A	
	1K x 16	Yes	Yes	Yes	Yes	Yes	N/A	N/A	
18Kbits	2K x 9	N/A	N/A	N/A	N/A	N/A	*	*	
	1K x 18	N/A	N/A	N/A	N/A	N/A	*	*	

Table 2-8 Read/Write Data Width Configuration in Semi Dual Port Mode

		Port A	Port A									
Capacity	Port B	16K x 1	8K x	4K x	2K x	1K x 16	512x 32	2K x	1K x 18	512 x 36	1K x 36	512 x 72
	16K x 1	Yes	Yes	Yes	Yes	Yes	Yes	N/A	N/A	N/A	N/A	N/A
	8K x 2	Yes	Yes	Yes	Yes	Yes	Yes	N/A	N/A	N/A	N/A	N/A
16l/hita	4K x 4	Yes	Yes	Yes	Yes	Yes	Yes	N/A	N/A	N/A	N/A	N/A
16Kbits	2K x 8	Yes	Yes	Yes	Yes	Yes	Yes	N/A	N/A	N/A	N/A	N/A
	1K x 16	Yes	Yes	Yes	Yes	Yes	Yes	N/A	N/A	N/A	N/A	N/A
	512 x 32	Yes	Yes	Yes	Yes	Yes	Yes	N/A	N/A	N/A	N/A	N/A
10Khita	2K x 9	N/A	N/A	N/A	N/A	N/A	N/A	Yes	Yes	Yes	N/A	N/A
18Kbits	1K x 18	N/A	N/A	N/A	N/A	N/A	N/A	Yes	Yes	Yes	N/A	N/A

Table 2-9 Read/Write Data Width Configuration in Semi Dual Port Mode with ECC Function(GW5A-138)

Capacity	Port B	Port A	
		1K x 36	512 x 72
36Kbits	512 x 72	N/A	*

# 2.4.4 ECC(GW5A-138)

The BSRAM of GW5A-138 has a built-in ECC hardcore module, which is mainly used for data detection and correction during data transfer and storage. ECC features are as follows:

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- ECC error detection and correction only supported in SDP 512 x 64 mode
- Supports 1-bit error correction and 2-bit error alarm in 64-bit SRAM data
- 72-bit ECC module contains 64-bit data bits and 8-bit parity bits;
- Bit 31 and bit 63 support 1-bit and 2-bit error injection

### 2.4.5 Byte-enable

BSRAMs in the GW5A series of FPGA products support the byteenable function. For data longer than a byte, the additional bits can be blocked, and only the selected portion can be written into. The byte enable function is for write only and is available at bit widths of 16/18 and 32/36. The blocked bits will be retained for future operation. Read/write enable ports (WREA, WREB), and byte parameter options can be used to control the BSRAM write operation.

## 2.4.6 Synchronous Operation

- All the input registers of BSRAM support synchronous write.
- The output register can be used as a pipeline register to improve design performance.
- The output registers are bypass-able.

## 2.4.7 Power up Conditions

BSRAM initialization is supported when powering up. During the power-up process, BSRAM is in standby mode, and all the data outputs are "0". This also applies in ROM mode.

# 2.4.8 BSRAM Operation Modes

BSRAM supports five different operations, including two read operations (Bypass Mode and Pipeline Read Mode) and three write operations (Normal Mode, Write-through Mode, and read-before-write Mode).

#### **Read Mode**

Read data from the BSRAM via output registers or without using the registers.

#### PIPELINE MODE

When reading data, the data is synchronously read out via the output register according to the clock beat. This mode supports up to 72-bit data width.

#### **BYPASS MODE**

In this mode, the output register is not used. When reading data, the data is directly sent to the output port.

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AD 🛚 **Pipeline** Input Memory DI [ DO. Register Register Array WRE CLK OCE □ ADB Input CLKA Register Input DIA Memory CLKB Register Array ADA **Pipeline** Register -OCEB DOB DIA DIB ADA Input ΔDR Input Register WRFA WRFR Register Memory Array CLKA CLKB Pipeline **Pipeline** Register Register **◄** OCEB **OCEA** DOA DOB

Figure 2-10 Pipeline Mode in Single Port, Dual Port, and Semi-Dual Port Mode

#### Write Mode

#### NORMAL MODE

In this mode, when the user writes data to one port, and the output data of this port does not change. The data written in will not appear at the read port.

#### WRITE-THROUGH MODE

In this mode, when the user writes data to one port, and the data written in will also appear at the output of this port.

#### READ-BEFORE-WRITE MODE[1]

In this mode, when the user writes data to one port, and the data written in will be stored in the memory according to the address. The original data in this address will appear at the output of this port.

#### Note!

[1] Only GW5A-25 supports read-before-write mode.

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#### 2.4.9 Clock Modes

Table 2-10 lists the clock modes in different BSRAM modes:

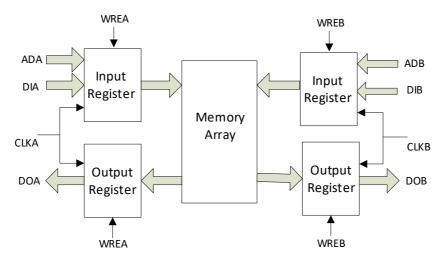
Table 2-10 Clock Modes in Different BSRAM Modes

Clock Mode	BSRAM Mode			
	Dual Port Mode	Semi Dual Port Mode	Single Port Mode	
Independent Clock Mode	Yes	No	No	
Read/Write Clock Mode	Yes	Yes	No	
Single Port Clock Mode	No	No	Yes	

#### **Independent Clock Mode**

Figure 2-11 shows the independent clocks in dual port mode with one clock at each port. CLKA controls all the registers at Port A; CLKB controls all the registers at Port B.

Figure 2-11 Independent Clock Mode

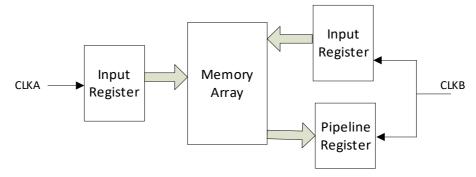


#### **Read/Write Clock Operation**

Figure 2-12 shows the read/write clock operations in the semi-dual port mode with one clock at each port. The write clock (CLKA) controls Port A data inputs, write address and read/write enable signals. The read clock (CLKB) controls Port B data output, read address, and read enable signals.

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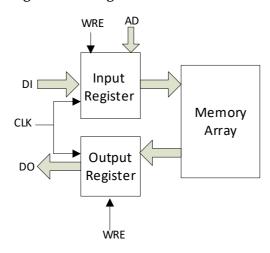
Figure 2-12 Read/Write Clock Mode



#### Single Port Clock Mode

Figure 2-13 shows the clock operation in single port mode.

Figure 2-13 Single Port Clock Mode



# 2.5 DSP Blocks

GW5A series of FPGA Products provide brand new DSP resources. This DSP solution can meet user demands for high performance digital signal processing design, such as FIR, FFT, etc. DSP blocks have the advantages of stable timing performance, high resource utilization, and low power consumption.

The features of DSP are as follows.

- Can be configured as 12 x 12, 27 x 28, and 27 x 36 signed multipliers
- 48-bit ALU
- Multipliers cascading to support wider data
- Barrel Shifter
- Adaptive filtering through signal feedback
- Supports pipeline mode and bypass mode.
- All operands for arithmetic operation are signed numbers
   Each DSP consists of three main parts:
- Input multiplexer and input registers;

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- One pre-adder, two multipliers, and pipeline registers;
- ALU, output multiplexers, and output registers.

#### 2.5.1 PADD

Each DSP features one PADD(pre-adder) for implementing pre-addition, pre-subtraction, and shifting.

PADD is located at the first stage with two inputs:

- 26-bit input C;
- Parallel 26-bit input A or SIA.

Each input end supports pipeline mode and bypass mode.

#### 2.5.2 MULT

Each DSP has one 27 x 18 multiplier M0 and one 12 x 12 multiplier M1. The multipliers are located after the pre-adders to implement multiplication operations, and both the inputs and outputs support register mode and bypass mode.

Multiplier M0 can be configured as:

- One 27 x 18 multiplier
- One 12 x 12 multiplier
- Two DSPs can form one 27 x 36 multiplier
   Multiplier M1 can only be configured as one 12 x 12 multiplier.

When multiplier M0 and multiplier M1 are both configured as a 12 x 12 multiplier and the ALU is enabled, 12 x 12 SUM mode can be achieved.

# 2.5.3 Arithmetic Logic Unit

Each DSP has one four-input 48-bit ALU, which can further enhance MULT's functions. Register mode and bypass mode are supported both in the inputs and outputs. The ALU supports the addition/subtraction operations of multiplier M0 output, multiplier M1 output(48bit operand D), ALU cascade input CASI, and ALU output feedback or static PRE\_LOAD value.

# 2.5.4 Operation Mode

Based on control signals, DSP can be configured as different operation modes. Operation Modes:

- Multiplier
- Accumulator
- MULTADDALU

For more information on DSP Blocks, see <u>UG305, Arora V Digital</u> <u>Signal Processing (DSP) User Guide</u>.

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#### 2.6 MIPI D-PHY

## 2.6.1 MIPI D-PHY RX(GW5A-138)

GW5A-138 provides a MIPI D-PHY RX hardcore supporting the "MIPI Alliance Standard for D-PHY Specification(V1.2)". The dedicated D-PHY core supports MIPI DSI and CSI-2 mobile video interfaces for cameras and displays. The main features are as follows:

- High Speed RX with the bandwidth up to 20 Gbps (eight data lanes).
- One MIPI Quad supports up to four data lanes and one clock lane.
- Bidirectional Low-power (LP) mode at up to 10Mbps per lane
- Built-in HS Sync, bit and lane alignment
- 1:8 and 1:16 deserialization modes to FPGA fabric's user interface
- Supports MIPI DSI and MIPI CSI-2 link layers

For more information on Gowin MIPI D-PHY RX/TX, pleae refer to *UG296, Arora V Hardened MIPI D-PHY User Guide*.

## 2.6.2 MIPI D-PHY RX/TX(GW5A-25)

GW5A-25 provides a MIPI D-PHY RX/TX hardcore supporting the "MIPI Alliance Standard for D-PHY Specification(V1.2)". The dedicated D-PHY core supports MIPI DSI and CSI-2 mobile video interfaces for cameras and displays. The main features are as follows:

- High Speed RX/TX with the bandwidth up to 10 Gbps (four data lanes)
- One MIPI Quad supports up to four data lanes and one clock lane.
- Bidirectional Low-power (LP) mode at up to 10Mbps per lane
- Built-in HS Sync, bit and lane alignment
- 1:8 and 1:16 deserialization modes to FPGA fabric's user interface
- Supports MIPI DSI and MIPI CSI-2 link layers

For more information on Gowin MIPI D-PHY RX/TX, pleae refer to *UG296, Arora V Hardened MIPI D-PHY User Guide*.

### **2.7 ADC**

The GW5A series of FPGA products integrate a new flexible analog interface as a temperature and power sensor. When combined with the programmable logic capability of the FPGA, the sensor can address the data acquisition and monitoring requirements for temperature and power monitoring.

Highlights of the sensor architecture include:

- On-chip reference, no off-chip voltage reference required
- 60dB SNR
- 10-bit oversampling @ 2MHz

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- 1kHz Signal Bandwidth
- two dedicated analog channels, able to detect input signals from GPIO at the same time
- On-chip temperature (±4°C max error) and voltage (±1% max error) sensors
- Continuous access to ADC measurements

The sensor optionally uses an on-chip reference circuit (±1%), thereby eliminating the need for any external active components for basic on-chip monitoring of temperature and power supply rails.

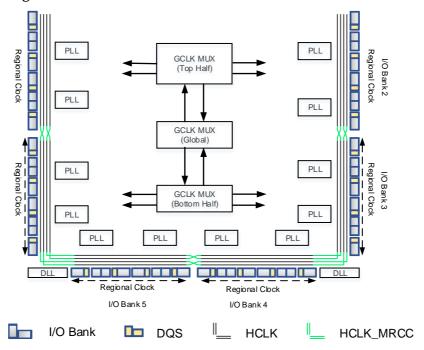
The most recent measurement results (together with maximum and minimum readings) are stored in dedicated registers for access at any time via the user interface.

For more information on ADC, see <u>UG299, Arora V Analog to Digital</u> Converter (ADC) User Guide.

#### 2.8 Clock

The clock resources and wiring are critical for high-performance applications in FPGA. GW5A series of FPGA products provide the global clock network (GCLK) which connects to all the registers directly. In addition to the GCLK, PLL, HCLK, DDR memory interface, and DQS, etc. are also provided.

Figure 2-14 GW5A-138 Clock Resources



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I/O Bank 7 I/O Bank 0 I/O Bank 1 ЛAG PLL PLL PLL GCLK MUX PLL PLL MP PLL I/O Bank 5 I/O Bank 4 I/O Bank 3 I/O Bank DQS HCLK

Figure 2-15 GW5A-25 Clock Resources

Please refer to 2.8.1 ~ 2.8.4 for a brief introduction. For further detailed information on the GCLK, HCLK, DDR memory interface, and DQS, see <u>UG306</u>, <u>Arora V Clock User Guide</u>.

#### 2.8.1 Global Clock

GW5A series FPGA products provide 16 global clocks. The clock source of GCLK comes from dedicated clock pins, PLL output, SERDES clock, HCLK output and common wiring resources. Dedicated clock input pins offer better clock performance and enable global driving.

#### 2.8.2 HCLK

HCLK is the high-speed clock with low jitter and low skew. It can support high-performance data transfer and is mainly suitable for source synchronous data transfer protocols. One bank supports 4 HCLKs, as

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#### shown in Figure 2-16 and Figure 2-17.

#### Figure 2-16 GW5A-138 HCLK Distribution

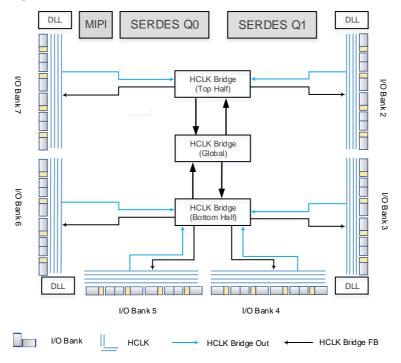
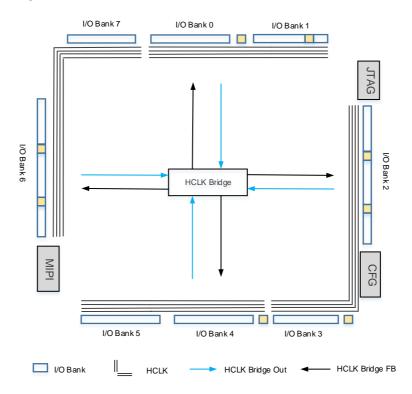


Figure 2-17 GW5A-138 HCLK Distribution



HCLK can provide users with the function modules as follows:

- Dynamic high-speed clock enable module. Able to dynamically turn on/off the high-speed clock signal.
- High speed clock frequency division module, generating a divided

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clock of the input clock. Used in the IO logic mode.

- Dynamic high speed clock selector.
- Dynamic delay adjustment module, producing the clock signal for the dedicated clock pin input.
- The HCLK bridge module is able to send HCLK clock signals to any of the Banks. In addition, the HCLK clock signal can span to the clock tree of the adjacent IO Bank after entering from the IO Bank.

#### Note!

For high speed signals of the same source, it is recommended to put them in the same IO Bank to achieve a minimum skew between signals.

## 2.8.3 Phase-locked Loop

PLL (Phase-locked Loop) is one kind of a feedback control circuit. The frequency and phase of the internal oscillator signal is controlled by the external input reference clock.

The PLL module of the GW5A series FPGA products can provide synthesizable clock frequencies. Frequency adjustment (multiply and division), phase adjustment, and duty cycle adjustment can be achieved by configuring the parameters.

The features of the PLL module of the GW5A series FPGA products are as follows:

- Supports seven clock outputs
- Integer PLL, the first clock output and feedback clock output support 1/8 fractional output division
- Supports phase shift and duty cycle adjustment
- Frequency Lock detection
- Supports spread spectrum clock generation (IP required)
- VCO frequency range: 800 MHz ~ 2000 MHz
- CLKIN frequency range: 10 MHz ~ 400 MHz.

# 2.8.4 DDR Memory Interface Clock Management DQS

The DQS module of the GW5A series of FPGA products provides the following features to support the clock requirements of the DDR memory interface:

- Receive DQS input, sort out waveform and shift 1/4 phase
- Provide a read / write pointer for input cache
- Provide valid data for internal logic
- Provide DDR output clock signal
- Support DDR3 write voltage control

The DQS module supports multiple operating modes to meet the

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needs of different I/O interfaces.

## 2.8.5 Long Wire

As a supplement to CRU, the GW5A series of FPGA products provide another routing resource- Long Wire, which is suitable for clock, clock enable, set/reset, or other high fan out signals.

# 2.9 Global Set/Reset (GSR)

A global set/rest (GSR) network is built in the GW5A series of FPGA product. There is a direct connection to core logic. It can be used as asynchronous/synchronous set. The registers in CFU and I/O can be individually configured to use GSR.

# 2.10 Programming & Configuration

The GW5A series of FPGA products support SRAM configuration. Each time the device is powered on, the bitstream needs to be downloaded to configure the device. Of course, you can also save the configuration data in an external Flash. After power-up, the GW5A device loads configuration data from the external Flash into the SRAM.

Besides JTAG, the GW5A series of FPGA products also support GOWINSEMI's own GowinCONFIG configuration mode: SSPI, MSPI, CPU, SERIAL. The FPGAs also support background programming, datastream file encryption and security bit setting, SEU detection and error correction, and OTP. For more information, please refer to <u>UG704, Arora V</u> <u>FPGA Products Programming and Configuration User Guide</u>.

#### **Background Upgrade**

GW5A series of FPGAs support background upgrade by JTAG/SSPI/QSSPI or UserLogic, that is, the device supports programming the embedded Flash or the external Flash without affecting the existing working state, the device can work normally according to the original configuration during the programming process. And after the programming is completed, trigger RECONFIG\_N with a low level to complete the online upgrade. This feature applies to the applications requiring long online time and irregular upgrades.

#### **Bitstream File Encryption & Security Bit Setting**

GW5A series of FPGA products support bitstream data encryption with 128-bit AES encryption algorithm. At the same time, GOWINSEMI adds CRC and sets security bits in the bitstream file of FPGA products by default in order to guarantee the safe and accurate transmission of configuration data. During the data configuration process, the input data is verified in real time for errors, and the device cannot be woken up by incorrect data. After the configuration of the bitstream with security bit is complete, data readback cannot be performed.

#### **CMSER (GW5A-138)**

The configuration SRAM of GW5A series of FPGA products supports

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configuration memory soft error recovery (CMSER), which are mainly used for data detection and correction of the FPGA configuration data and are disabled by default. The features are as follows:

- Supports ECC and CRC error detection and correction. Turning on the auto-on mode after wakeup according to the user configuration or using the user design logic control to turn on/off error detection and correction
- ECC supports 1-bit error location report and error correction and 2-bit error alarm per 64-bit SRAM data
- CRC supports any bit error alarm
- Supports 1-bit error injection at any position, one error per 64-bit SRAM data
- The detection and error correction function of SRAM in this storage area will be automatically turned off when the user turns on the SSRAM storage function

#### CMSER (GW5A-25)

The configuration SRAM of GW5A series of FPGA products supports configuration memory soft error recovery (CMSER), which are mainly used for data detection and correction of the FPGA configuration data and are disabled by default. The features are as follows:

- Supports ECC and CRC error detection and correction. Turning on the auto-on mode after wakeup according to the user configuration or using the user design logic control to turn on/off error detection and correction
- ECC supports 2-bit error location report and error correction and 4-bit error alarm in each SRAM Frame
- CRC supports any bit error alarm
- Supports 1-bit error injection at any position, two errors in each SRAM Frame
- The detection and error correction function of SRAM in this storage area will be automatically turned off when the user turns on the SSRAM storage function

#### **mDRP**

GW5A series FPGA products support independent mDRP ports, allowing point-to-point structure access.

#### **OTP**

GW5A series of FPGAs provide a 128-bit OTP space and support one-time programming. Bit0 ~ Bit31 is the user space, which can be used to store security and other important information. Bit32~Bit95 is the DNA space, which stores the 64-bit unique identification information of the device.

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# 2.11 On Chip Oscillator

There is an internal oscillator in each of the GW5A series of FPGA products. During the configuration process, it can provide a clock for the MSPI mode. The on-chip oscillator also provides a clock resource for user designs. Up to 64 clock frequencies can be obtained by setting the parameters. The following formula is employed to get the output clock frequency:

fout=210MHz/Param.

#### Note!

"Param" is the configuration parameter. It should 3 or an even number between 2 and 126.

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# 3 AC/DC Characteristics

#### Note!

You should ensure GOWINSEMI® products are always used within recommended operating conditions and range. Data beyond the working conditions and range are for reference only. GOWINSEMI® does not guarantee that all devices will operate as expected beyond the standard operating conditions and range.

# 3.1 Operating Conditions

## 3.1.1 Absolute Max. Ratings

Table 3-1 Absolute Max. Ratings

Name	Description	Min.	Max.			
FPGA Logic						
V <sub>CC</sub> (GW5A-138)	Core voltage	-0.5V	1.05V			
V <sub>cc</sub> (GW5A-25)	Core voltage, LV	-0.5V	1.05V			
VCC(OVVO/ (20)	Core voltage, EV	-0.5V	3.75V			
V <sub>CCIO</sub>	I/O Bank voltage	-0.5V	3.75V			
M0_VDD_12 (GW5A-25)	Power supply pin of MIPI LP voltage.	-0.5V	1.32V			
V <sub>CCX</sub> (GW5A-138)	Auxiliary voltage	-0.5V	1.98V			
V <sub>CCX</sub> (GW5A-25)	Auxiliary voltage	-0.5V	3.75V			
V <sub>CC_REG</sub>	Regulator voltage	-0.5V	3.75V			
V <sub>IN</sub>	Single-ended input	-0.4V	3.75V			
VIN	Differential input	-0.4V	2.625V			
MIPI						
$V_{dda}$	Analog core power supply	-0.5V	1.05V			
$V_{ddx\_dphy}$	Analog high voltage power supply	-0.5V	1.98V			
Temperature						
Storage Temperature	Temperature Storage Temperature		+150℃			
Junction Temperature	Junction Temperature	-40 □	+125℃			

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# 3.1.2 Recommended Operating Conditions

Table 3-2 Recommended Range

Name	Description	Min.	Max.
V <sub>CC</sub> (GW5A-138)	Core voltage	0.87V	1.0V
V (C)MEA 35)	Core voltage, LV	0.855V	1.0V
V <sub>CC</sub> (GW5A-25)	Core voltage, EV <sup>[1]</sup>	1.14V	1.8V
V <sub>CCIO</sub>	I/O Bank voltage	1V	3.465V
V <sub>CCX</sub> (GW5A-138)	Auxiliary voltage	1.71V	1.89V
V <sub>CCX</sub> (GW5A-25)	Auxiliary voltage	2.375V	3.465V
M0_VDD_12 (GW5A-25)	Power supply pin of MIPI LP voltage.	1.14V	1.32V
V <sub>CC_REG</sub>	Regulator voltage	1.14V	3.3V
MIPI			
$V_{dda}$	Analog core power supply	0.87V	1.0V
$V_{ddx\_dphy}$	Analog high voltage power supply	1.71V	1.89V
Temperature			
Т <sub>ЈСОМ</sub>	Junction temperature Commercial operation Junction temperature Commercial operation	0 🗆	+85 □
T <sub>JIND</sub>	Junction temperature Industrial operation (Junction temperature Commercial operation)	-40℃	+100℃

#### Note!

- [1] The 1.2V core voltage of EV version devices is generated by the built-in LDO. The higher the Vcc voltage, the higher the system power consumption.
- [2] Please refer to <u>UG982, GW5A-138 Pinout</u> and <u>UG985, GW5A-138 Pinout</u> for the supply voltage information of the devices in different packages.

# 3.1.3 Power Supply Ramp Rates

**Table 3-3 Power Supply Ramp Rates** 

Name	Description	Min.	Тур.	Max.
T <sub>RAMP</sub>	Power supply ramp rates	0.02mV/µs	TBD	50mV/µs

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# 3.1.4 Hot Socket Specifications

**Table 3-4 Hot Socket Specifications** 

Name	Description	Condition	I/O	Max.
I <sub>HS</sub>	Input leakage current (Input or I/O leakage current)	V <sub>IN</sub> =V <sub>IL</sub> (MAX)	I/O	TBD
I <sub>HS</sub>	Input leakage current (Input or I/O leakage current)	V <sub>IN</sub> =V <sub>IL</sub> (MAX)	TDI, TDO TMS,TCK	TBD

# 3.1.5 POR Specifications

**Table 3-5 POR Parameters** 

Name	Description	Device	Name	Тур.
DOD			V <sub>CC</sub>	0.72V
POR Voltage	Power on reset voltage	GW5A-138	V <sub>CCX</sub>	1.5V
voitage			V <sub>CCIO</sub> (Bank10)	1.04V

# 3.2 ESD performance

Table 3-6 GW5A ESD - HBM

Device	НВМ
GW5A-25	HBM > 2000V
GW5A-138	HBM > 1000V

Table 3-7 GW5A ESD - CDM

Device	GW5A-25
GW5A-25	CDM > 500V
GW5A-138	CDM > 250V

# 3.3 DC Characteristics

# 3.3.1 DC Electrical Characteristics over Recommended Operating

#### **Conditions**

Table 3-8 DC Electrical Characteristics over Recommended Operating Conditions

Name	Description	Condition	Min.	Тур.	Max.
L. L.	Input or I/O leakage	V <sub>CCIO</sub> <v<sub>IN<v<sub>IH (MAX)</v<sub></v<sub>	-	TBD	TBD
$I_{IL},I_{IH}$	input of 1/O leakage	0V <v<sub>IN<v<sub>CCIO</v<sub></v<sub>	-	TBD	TBD
I <sub>PU</sub>	I/O Active Pull-up Current	0 <v<sub>IN&lt;0.7V<sub>CCIO</sub></v<sub>	-	TBD	TBD
I <sub>PD</sub>	I/O Active Pull-down Current	V <sub>IL</sub> (MAX) <v<sub>IN<v<sub>CCIO</v<sub></v<sub>	-	TBD	TBD
C1	I/O Capacitance	_	-	9pF	TBD
V <sub>HYST</sub>	Hysteresis for Schmitt	V <sub>CCIO</sub> = 3.3V, Hysteresis=L2H	-	250	TBD
VHYST	Trigger inputs	V <sub>CCIO</sub> = 2.5V, Hysteresis=L2H	-	90	TBD

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Name	Description	Condition	Min.	Тур.	Max.
		V <sub>CCIO</sub> = 1.8V, Hysteresis=L2H	-	50	TBD
		V <sub>CCIO</sub> = 1.5V, Hysteresis=L2H	-	40	TBD
		V <sub>CCIO</sub> = 1.2V, Hysteresis=L2H		40mV	TBD
		V <sub>CCIO</sub> = 3.3V, Hysteresis=H2L	-	310	TBD
		V <sub>CCIO</sub> = 2.5V, Hysteresis=H2L	-	130	TBD
		V <sub>CCIO</sub> = 1.8V, Hysteresis=H2L	-	50	TBD
		V <sub>CCIO</sub> = 1.5V, Hysteresis=H2L	-	30	TBD
		V <sub>CCIO</sub> = 1.2V, Hysteresis=H2L		30mV	TBD
		V <sub>CCIO</sub> = 3.3V, Hysteresis=High	-	560	TBD
		V <sub>CCIO</sub> = 2.5V, Hysteresis=High	-	220	TBD
		V <sub>CCIO</sub> = 1.8V, Hysteresis=High	-	100	TBD
		V <sub>CCIO</sub> = 1.5V, Hysteresis=High	-	70	TBD
		V <sub>CCIO</sub> = 1.2V, Hysteresis=High		70mV	TBD

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#### 3.3.2 Static Current

**Table 3-9 Static Current** 

Name	Description	LV/UV	Device	Typ. <sup>[1]</sup>
Icc	Core Current	LV version	GW5A-138	100 mA
Iccx	V <sub>CCX</sub> current (V <sub>CCX</sub> =2.5V)	LV version	GW5A-138	9 mA
Iccio	I/O Bank current (V <sub>CCIO</sub> =3.3V)	LV version	GW5A-138	5 mA
I <sub>CC_REG</sub>	Built-in regulator static current	LV version	GW5A-138	6 mA

#### Note!

[1] Typical values are tested at 25°C.

# 3.3.3 Recommended I/O Operating Conditions

Table 3-10 I/O Operating Conditions Recommended

Name	Output Vcc	io (V)		Input V <sub>REF</sub> (V)		
Name	Min.	Тур.	Max.	Min.	Тур.	Max.
LVTTL33	3.135	3.3	3.465	-	-	-
LVCMOS33	3.135	3.3	3.465	-	-	-
LVCMOS25	2.375	2.5	2.625	-	-	-
LVCMOS18	1.71	1.8	1.89	-	-	-
LVCMOS15	1.425	1.5	1.575	-	-	-
LVCMOS12	1.14	1.2	1.26	-	-	-
SSTL15	1.425	1.5	1.575	0.68	0.75	0.9
SSTL18_I	1.71	1.8	1.89	0.833	0.9	0.969
SSTL18_II	1.71	1.8	1.89	0.833	0.9	0.969
SSTL25_I	2.375	2.5	2.645	1.15	1.25	1.35
SSTL25_II	2.375	2.5	2.645	1.15	1.25	1.35
SSTL33_I	3.135	3.3	3.465	1.3	1.5	1.7
SSTL33_II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL18_I	1.71	1.8	1.89	0.816	0.9	1.08
HSTL18_II	1.71	1.8	1.89	0.816	0.9	1.08
HSTL15	1.425	1.5	1.575	0.68	0.75	0.9
PCI33	3.135	3.3	3.465	-	-	-
LVPECL33E	3.135	3.3	3.465	-	-	-
MLVDS25E	2.375	2.5	2.625	-	-	-
BLVDS25E	2.375	2.5	2.625	-	-	-
RSDS25E	2.375	2.5	2.625	-	-	-
LVDS25E <sup>1</sup>	2.375	2.5	2.625	-	-	-
SSTL15D	1.425	1.5	1.575	-	-	-

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Name	Output V <sub>CC</sub>	<sub>IO</sub> (V)	Input V <sub>REF</sub> (V)			
Name	Min.	Тур.	Max.	Min.	Тур.	Max.
SSTL18D_I	1.71	1.8	1.89	-	-	-
SSTL18D_II	1.71	1.8	1.89	-	-	-
SSTL25D_I	2.375	2.5	2.625	-	-	-
SSTL25D_II	2.375	2.5	2.625	-	-	-
SSTL33D_I	3.135	3.3	3.465	-	-	-
SSTL33D_II	3.135	3.3	3.465	-	-	-
HSTL15D	1.425	1.575	1.89	-	-	-
HSTL18D_I	1.71	1.8	1.89	-	-	-
HSTL18D_II	1.71	1.8	1.89	-	-	-

#### Note!

 $V_{\text{CCIO}}$  of Banks with True LVDS is recommended to be set to 2.5 V.

# 3.3.4 Single-ended I/O DC Characteristics

Table 3-11 Single-ended DC Characteristics

Name	VIL		V <sub>IH</sub>		V <sub>OL</sub>	V <sub>OH</sub>	I <sub>OL</sub> [1]	I <sub>OH</sub> <sup>[1]</sup>
Name	Min	Max	Min	Max	(Max)	(Min)	(mA)	(mA)
							4	-4
							8	-8
LVCMOS33				V <sub>CCIO</sub>	0.4V	V <sub>CCIO</sub> - 0.4 V.	12	-12
LVTTL33	-0.3V	0.8V	2.0V	+0.3			16	-16
							24	-24
					0.2V	V <sub>CCIO</sub> - 0.2 V.	0.1	-0.1
							4	-4
		0.7V	1.7V		0.40	V <sub>CCIO</sub> - 0.4	8	-8
LVCMOS25 -0	-0.3V			V <sub>CCIO</sub> +0.3		V.	12	-12
				+0.3			16	-16
					0.2V	V <sub>CCIO</sub> - 0.2 V.	0.1	-0.1
				V <sub>CCIO</sub> +0.3		V <sub>CCIO-</sub> 0.4 V.	4	-4
					0.4V		8	-8
LVCMOS18	-0.3V	0.35 x V <sub>CCIO</sub>	0.65 x V <sub>CCIO</sub>				12	-12
					0.2V	V <sub>CCIO</sub> - 0.2 V.	0.1	-0.1
					0.4V	V <sub>CCIO</sub> - 0.4	4	-4
LVCMOS15	-0.3V	0.35 x V <sub>CCIO</sub>	0.65 x V <sub>CCIO</sub>	V <sub>CCIO</sub> +0.3	0.4 V	V.	8	-8
		33,0			0.2V	V <sub>CCIO</sub> - 0.2 V.	0.1	-0.1
LVCMOS12	0.317	0.3V 0.35 x V <sub>CCIO</sub>	0.65 x V <sub>CCIO</sub>	V <sub>CCIO</sub>	0.4V	V <sub>CCIO</sub> - 0.4 V.	2	-2
LV CIVIOS 12	-0.50			+0.3			4	-4

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Name	V <sub>IL</sub>		V <sub>IH</sub>		V <sub>OL</sub>	Voн	l <sub>OL</sub> <sup>[1]</sup>	I <sub>OH</sub> <sup>[1]</sup>
INAIIIC	Min	Max	Min	Max	(Max)	(Min)	(mA)	(mA)
					0.2V	V <sub>CCIO</sub> - 0.2 V.	0.1	-0.1
LVCMOS10	-0.3	0.35 x V <sub>CCIO</sub>	0.65 x V <sub>CCIO</sub>	V <sub>CCIO</sub> +0.3	0.4V	V <sub>CCIO</sub> - 0.4 V.	4	-4
PCI33	-0.3V	0.3 x V <sub>CCIO</sub>	0.5 x V <sub>CCIO</sub>	V <sub>CCIO</sub> +0.3	0.1 x V <sub>CCIO</sub>	0.9 x V <sub>CCIO</sub>	1.5	-0.5
SSTL18_II	-0.3V	V <sub>REF</sub> -0.125V	V <sub>REF</sub> +0.125V	V <sub>CCIO</sub> +0.3	0.4V	V <sub>CCIO-</sub> 0.4 V.	NA	NA
SSTL18_I	-0.3V	V <sub>REF</sub> -0.125V	V <sub>REF</sub> +0.125V	V <sub>CCIO</sub> +0.3	0.40V	V <sub>CCIO</sub> - 0.40V	8	-8
SSTL15	-0.3V	V <sub>REF</sub> -0.1V	V <sub>REF</sub> + 0.1 V.	V <sub>CCIO</sub> +0.3	0.40V	V <sub>CCIO</sub> - 0.40V	8	-8
SSTL135	-0.3	V <sub>REF</sub> -0.09V	V <sub>REF</sub> +0.09V	V <sub>CCIO</sub> +0.3	0.40V	V <sub>CCIO</sub> - 0.40V	8	-8
HSTL18_I	-0.3V	V <sub>REF</sub> -0.1V	V <sub>REF</sub> + 0.1 V.	V <sub>CCIO</sub> +0.3	0.40V	V <sub>CCIO</sub> - 0.40V	8	-8
HSTL18_II	-0.3V	V <sub>REF</sub> -0.1V	V <sub>REF</sub> + 0.1 V.	V <sub>CCIO</sub> +0.3	0.40 V	V <sub>CCIO</sub> - 0.40V	NA	NA
HSTL15_I	-0.3V	V <sub>REF</sub> -0.1V	V <sub>REF</sub> + 0.1 V.	V <sub>CCIO</sub> +0.3	0. <del>4</del> 0 V	V <sub>CCIO</sub> - 0.40V	8	-8
HSTL15_II	-0.3V	V <sub>REF</sub> -0.1V	V <sub>REF</sub> + 0.1 V.	V <sub>CCIO</sub> +0.3	0.40V	V <sub>CCIO</sub> - 0.40V	NA	NA
HSUL12	-0.3	V <sub>REF</sub> -0.13V	V <sub>REF</sub> + 0.13V	V <sub>CCIO</sub> +0.3	0.40	V <sub>CCIO</sub> - 0.40V	0.1	-0.1

#### Note!

[1] The total DC current limit(sourced and sinked) of all IOs in the same bank: the total DC current of all IOs in the same bank shall not be greater than n\*8mA, where n represents the number of IOs bonded out from a bank.

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# 3.3.5 Differential I/O DC Characteristic

Table 3-12 Differential I/O DC Characteristic

Name	Description	Conditions	Min.	Тур.	Max.	Unit
$V_{\text{INA}}, V_{\text{INB}}$	Input Voltage	TBD	-0.4		2.625	V
V <sub>CM</sub>	Input Common Mode Voltage	Half the Sum of the Two Inputs	0.3	1.2	1.5	V
V <sub>THD</sub>	Differential Input Threshold	Difference Between the Two Inputs	±70	±200	±300	mV
I <sub>IN</sub>	Input Current	Power On or Power Off	TBD	TBD	TBD	μA
V <sub>OH</sub>	Output High Voltage for VOP or VOM	R <sub>T</sub> = 100 Ω	TBD	TBD	1.675	V
V <sub>OL</sub>	Output High Voltage for VOP or VOM	R <sub>T</sub> = 100 Ω	0.7	TBD	TBD	V
V <sub>OD</sub>	Output Voltage Differential	$(V_{OP} - V_{OM}), R_T = 100\Omega$	250	350	600	mV
$\Delta V_{OD}$	Change in VOD Between High and Low	TBD	TBD	TBD	50	mV
Vos	Output Voltage Offset	$(V_{OP} + V_{OM})/2$ , $R_T = 100\Omega$	1.000	1.250	1.425	V
ΔV <sub>OS</sub>	Change in VOS Between High and Low	TBD	TBD	TBD	TBD	mV
Is	Short-circuit current	V <sub>OD</sub> = 0V output short-circuit	TBD	TBD	TBD	mA

# 3.4 AC Switching Characteristics

# 3.4.1 CFU Switching Characteristics

**Table 3-13 CFU Timing Parameters** 

Name	Description	Speed	Unit		
Ivallie	Description	Min	Max	Offic	
t <sub>LUT4_CFU</sub>	LUT4 delay	-	-	ns	
t <sub>SR_CFU</sub>	Set/Reset to Register output	-	-	ns	
t <sub>CO_CFU</sub>	Clock to Register output	-	-	ns	

# 3.4.2 BSRAM Switching Characteristics

**Table 3-14 BSRAM Timing Parameters** 

Name	Description	Speed Grade		Unit	
INAITIE	Description	Min	Max	Offic	
t <sub>COAD_BSRAM</sub>	Clock to output from read address/data	-	-	ns	
t <sub>COOR</sub> BSRAM	Clock to output from output register	-	-	ns	

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# 3.4.3 DSP Switching Characteristics

**Table 3-15 DSP Timing Parameters** 

Name	Description	Speed Grade		Unit
INAITIE	Description	Min	Max	Offic
t <sub>COIR_DSP</sub>	Clock to output from input register	-	-	ns
t <sub>COPR_DSP</sub>	Clock to output from pipeline register	-	-	ns
tcoor_dsp	Clock to output from output register	-	-	ns

# 3.4.4 Clock and I/O Switching Characteristic

**Table 3-16 External Switching Characteristics** 

Name Description		Device	-8		-7		Unit
Name	Description	Device	Min	Max	Min	Max	Offic
Pin-LUT-Pin Delay <sup>(1)</sup>	Pin(IOxA) to Pin(IOxB) delay	GW5A-138	1	1	ı	1	ns
T <sub>HCLKdly</sub>	HCLK tree delay	GW5A-138	-	-	-	-	ns
T <sub>GCLKdly</sub>	GCLK tree delay	GW5A-138	-	-	-	-	ns

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# 3.4.5 On chip Oscillator Switching Characteristics

Table 3-17 On chip Oscillator Switching Characteristics

Device	Name	Description	Min.	Тур.	Max.
	f	Output Frequency (0 to + 85° C)	199.5 MHz	210MHz	220.5MHz
GW5A- 138	T <sub>MAX</sub>	Output Frequency (-40 to +100° C)	189 MHz	210MHz	231MHz
100	t <sub>DT</sub>	Output Clock Duty Cycle	-	50%	-
	t <sub>OPJIT</sub>	Output Clock Period Jitter	TBD	TBD	TBD

# 3.4.6 PLL Switching Characteristics

**Table 3-18 PLL Switching Characteristic** 

Device	Name	Min.	Max.
GW5A-138	CLKIN	10MHz	400MHz
	PFD	10MHz	400MHz
	VCO	800MHz	2GHz
	CLKOUT	6.25MHz <sup>[1]</sup>	1GHz

#### Note!

6.25MHz is the minimum frequency of CLKOUT in non-cascade mode.

# 3.5 Configuration Interface Timing Specification

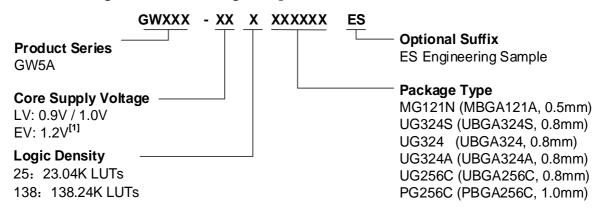
The GW5A series of FPGA Products support multiple GowinCONFIG modes: SSPI, MSPI, SERIAL, and CPU. For more detailed information, please refer to <u>UG704, Arora V FPGA Products Programming and Configuration Guide</u>.

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# 4 Ordering Information

#### 4.1 Part Name

Figure 4-1 Part Naming Examples-ES

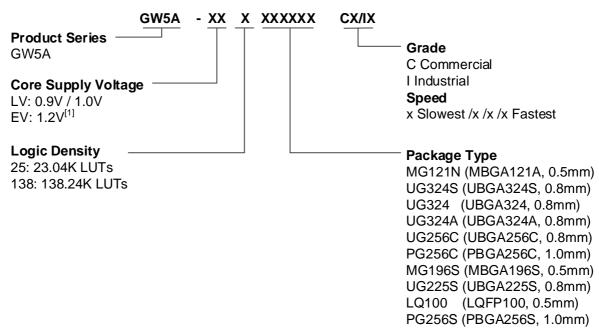


#### Note!

[1] Currently, GW5A-25 of the GW5A series devices supports the EV version.

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Figure 4-2 Part Naming Examples-Production



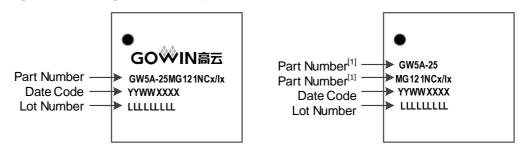
#### Note!

- [1] Currently, GW5A-25 of the GW5A series devices supports the EV version.
- For the further detailed information about the package information, please refer to 1.2 Product Resources.
- he LittleBee® family devices and Arora family devices of the same speed grade have different speeds.
- Both "C" and "I" are used in GOWIN part name marking for one device, such as C8/I7, C6/I5, etc. GOWIN devices are screened using industrial standards, so one same device can be used for both industrial (I) and commercial (C) applications. The maximum temperature of the industrial grade is 100, and the maximum temperature of the commercial grade is 85. Therefore, if the same chip meets the speed grade 8 in the commercial grade application, the speed grade is 7 in the industrial grade application.

# 4.2 Package Mark

The device information of GOWINSEMI is marked on the chip surface, as shown in Figure 4-3.

Figure 4-3 Package Mark Examples



#### Note!

[1] The first two lines in the right figure above are the "Part Number".

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# 5 About This Guide

# 5.1 Purpose

This data sheet describes the features, product resources, structure, AC/DC characteristics, and the ordering information of the GW5A series of FPGA products, making it easier to understand the GW5A series of FPGA products and select and use our devices.

# 5.2 Related Documents

The latest user guides are available on the GOWINSEMI Website. You can find the related documents at <a href="https://www.gowinsemi.com">www.gowinsemi.com</a>:

- <u>UG704, Arora V FPGA Products Programming and Configuration User Guide</u>
- UG983, GW5A series of FPGA Products Package and Pinout Manual
- UG985, GW5A-25 Pinout
- UG988, GW5A-138 Pinout
- UG984, Arora V FPGA Products Schematic Manual

# 5.3 Terminology and Abbreviations

The terminology and abbreviations used in this manual are as shown in Table 5-1.

Table 5-1 Terminology and Abbreviations

Terminology and Abbreviations	Full Name
ADC	Analog to Digital Converter
AER	Advanced Error Reporting
ALU	Arithmetic Logic Unit
BSRAM	Block Static Random Access Memory
CFU	Configurable Function Unit
CLS	Configurable Logic Section
CMSER	Configuration Memory Soft Error Recovery
CRU	Configurable Routing Unit

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Terminology and Abbreviations	Full Name
CSI	Camera Serial Interface
CTC	Clock Tolerance Compensation
CTLE	Continuous Time Linear Equalizer
DCS	Dynamic Clock Selector
DFF	D Flip-floor
DNA	Device Identifier
DP	True Dual Port 16K BSRAM
DSI	Display Serial Interface
DSP	Digital Signal Processing
ECC	Error Correction Code
ECRC	End-to-End Cyclic Redundancy Check
ESD	Electro-Static Discharge
FIFO	First In First Out
FPG	FCPBGA
FPGAs	Field Programmable Gate Array
GCLK	Global Clock
GPIO	Gowin Programmable IO
GSR	Global Set/Reset
HCLK	High Speed Clock
IOB	Input/Output Block
LUT	Look-up Table
LW	Long Wire
MIPI	Mobile Industry Processor Interface
OTP	One Time Programmable
PLL	Phase-locked Loop
REG	Register
SDP	Semi Dual Port 16K BSRAM
SP	Single Port 16K BSRAM
SSRAM	Shadow Static Random Access Memory
TDM	Time Division Multiplexing

# 5.4 Support and Feedback

Gowin Semiconductor provides customers with comprehensive technical support. If you have any questions, comments, or suggestions, please feel free to contact us directly using the information provided below.

Website: <a href="www.gowinsemi.com">www.gowinsemi.com</a>
E-mail: <a href="mailto:support@gowinsemi.com">support@gowinsemi.com</a>

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# Preliminary

